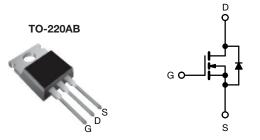
Vishay Siliconix

HALOGEN

**FREE** 

# **E Series Power MOSFET**



N-Channel MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	65	50		
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.086		
Q <sub>g</sub> max. (nC)	5	0		
Q <sub>gs</sub> (nC)	1	3		
Q <sub>gd</sub> (nC)	1	0		
Configuration	Sin	Single		

### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

## **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP100N60E-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	600	V	
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$	- I <sub>D</sub>	30		
		T <sub>C</sub> = 100 °C		19	A	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	73		
Linear derating factor				1.67	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	226	mJ	
Maximum power dissipation			$P_{D}$	208	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	70	)//		
Reverse diode dv/dt <sup>d</sup>			23	- V/ns		
Soldering recommendations (peak temperature) c	For 10 s			260	°C	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 4.0 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	-	62	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.6	C/VV	

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.73	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
Onto anima lankana		,	$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	$V_{GS} = \pm 30 \text{ V}$		-	± 1	μA
7		V <sub>DS</sub> =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 13 A	-	0.086	0.1	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 8 V, I <sub>D</sub> = 13 A		-	11	-	S
Dynamic		•					
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V,		-	1851	-	pF
Output capacitance	C <sub>oss</sub>	Τ,	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 100 V,		84	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz		-	5	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	64	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	407	-	
Total gate charge	Qg			-	33	50	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	V <sub>GS</sub> = 10 V I <sub>D</sub> = 13 A, V <sub>DS</sub> = 480 V		13	-	nC
Gate-drain charge	Q <sub>gd</sub>			-	10	-	1
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD} = 480 \text{ V}, I_{D} = 13 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	21	42	
Rise time	t <sub>r</sub>			-	34	68	
Turn-off delay time	t <sub>d(off)</sub>			-	33	66	ns
Fall time	t <sub>f</sub>			-	20	40	
Gate input resistance	$R_g$	f = 1	f = 1 MHz, open drain		0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I <sub>S</sub>	showing the			-	30	
Pulsed diode forward current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	73	Α
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 13 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 13 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	358	716	ns
Reverse recovery charge	Q <sub>rr</sub>			-	5.1	10.2	μC
Reverse recovery current	I <sub>RRM</sub>			_	24	_	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$
- $b. \ \ C_{oss(tr)} \ is \ a \ fixed \ capacitance \ that \ gives \ the \ same \ charging \ time \ as \ C_{oss} \ while \ V_{DS} \ is \ rising \ from \ 0 \ \% \ to \ 80 \ \% \ V_{DSS}$



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

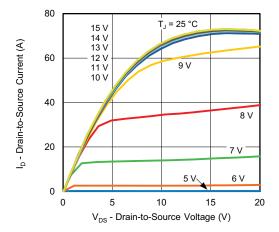


Fig. 1 - Typical Output Characteristics

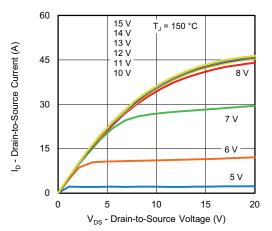


Fig. 2 - Typical Output Characteristics

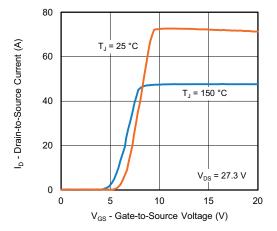


Fig. 3 - Typical Transfer Characteristics

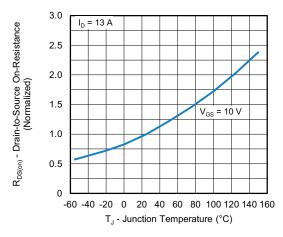


Fig. 4 - Normalized On-Resistance vs. Temperature

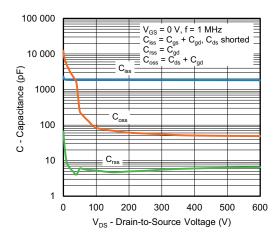


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

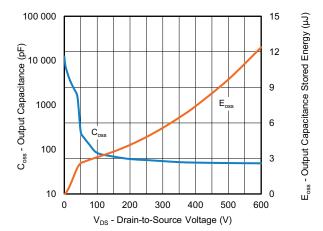


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



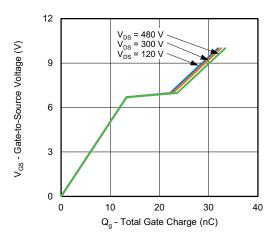


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

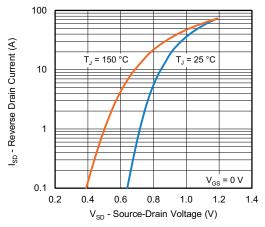


Fig. 8 - Typical Source-Drain Diode Forward Voltage

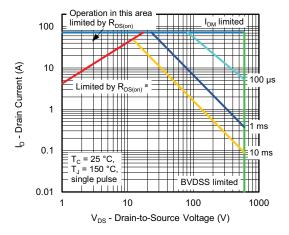


Fig. 9 - Maximum Safe Operating Area



a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

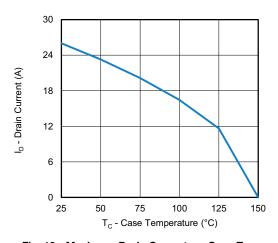


Fig. 10 - Maximum Drain Current vs. Case Temperature

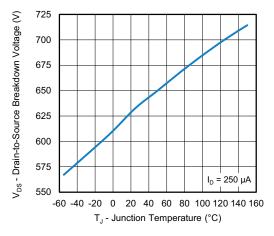


Fig. 11 - Temperature vs. Drain-to-Source Voltage



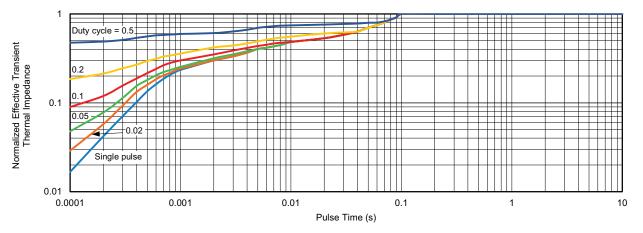


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

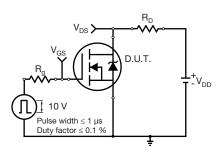


Fig. 13 - Switching Time Test Circuit

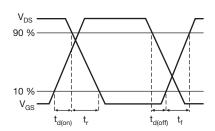


Fig. 14 - Switching Time Waveforms

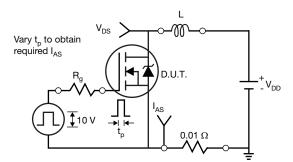


Fig. 15 - Unclamped Inductive Test Circuit

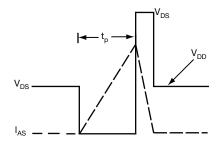


Fig. 16 - Unclamped Inductive Waveforms

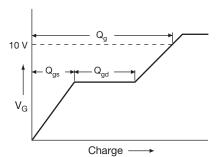


Fig. 17 - Basic Gate Charge Waveform

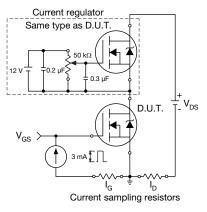
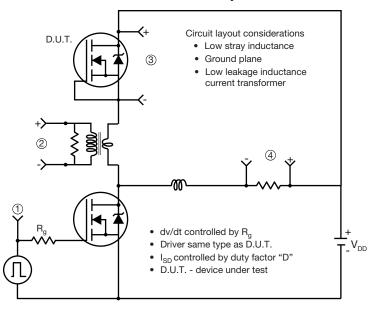


Fig. 18 - Gate Charge Test Circuit



## Peak Diode Recovery dv/dt Test Circuit



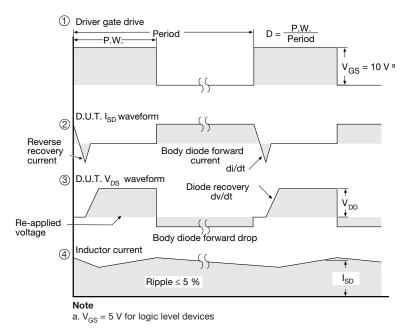


Fig. 19 - For N-Channel

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